Tool ID: 800
Tool Location: TBD

Equipment Information Sheet

nanoBOND Temporary Bonding and Debonding System

Manager: Garry Bordonaro 607-254-4936 Calls to staff phones will be automatically forwarded to their cell phones during accessible hours. At other times leave a message or send them an email.

SAFETY

WARNING: Hot Surfaces!

USAGE RESTRICTIONS

SCHEDULING/SIGN-UP RESTRICTIONS

Minimum Tool Time: 30 minutes

MATERIALS COMPATIBILITY CATEGORY

Tool Category 1:Restriced Silicon Based Materials Only

Allowed	Not Allowed
Silicon Based Materials only (Si, SiC, SiO_2 substrates)	No Evaporated, Sputtered, or Spin on Films
All Furnace grown or deposited films	No ALD films
PECVD Films	No Metal or Organic Films
	No Glass Substrates
	No III/V Compound Semiconductors
	No Deep Silicon Etched Samples (versaline, Unaxis)
	No Organic/Biology Molecules prepared-with or without Salt buffers

Additional Material Restrictions and Exceptions

Last Updated: 05/06/2026